微纳光电子材料与器件工艺原理

Emerging Technologies

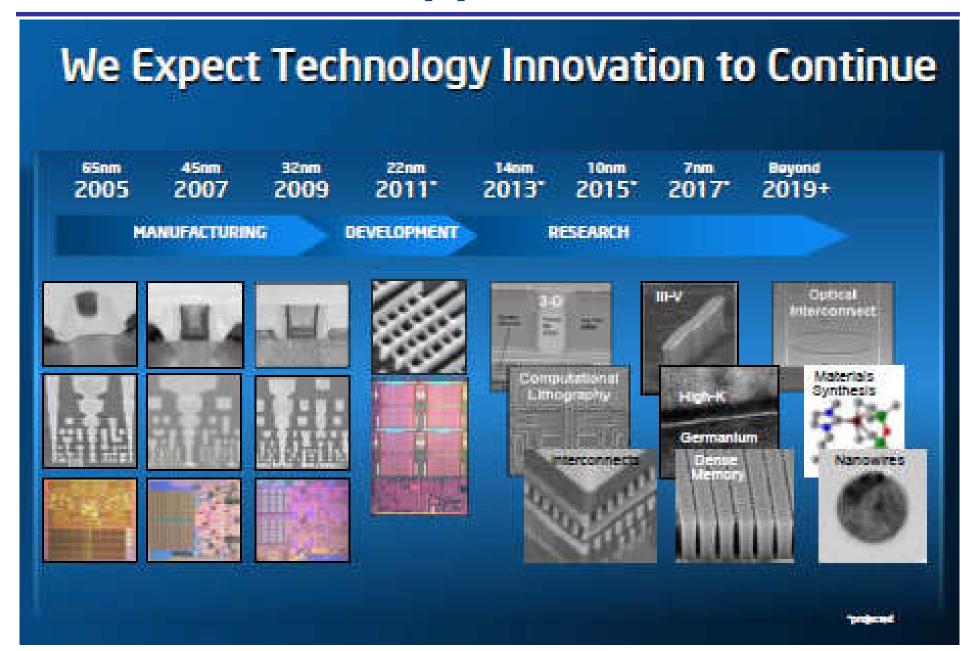
Xing Sheng 盛 兴



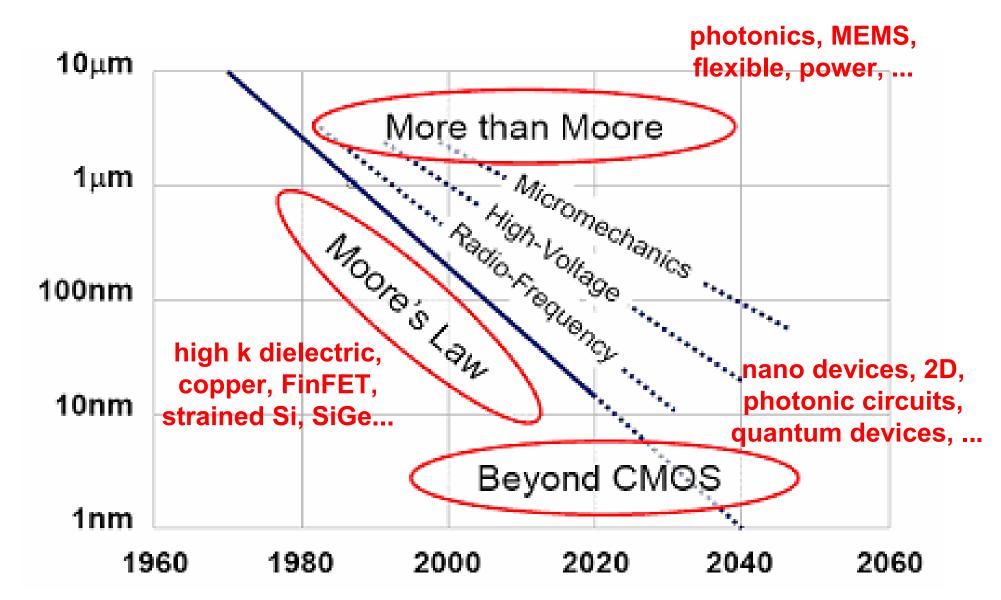
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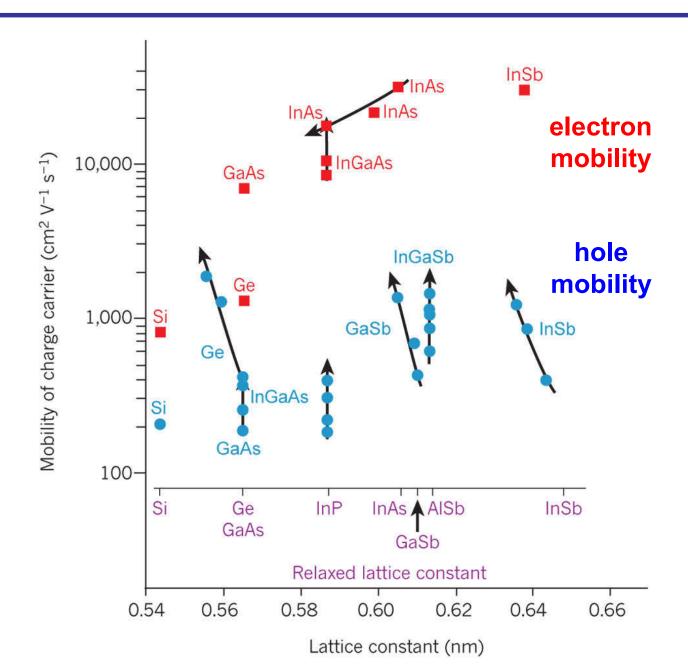
New Opportunities



New Opportunities



High Electron Mobility Transistor (HEMT)

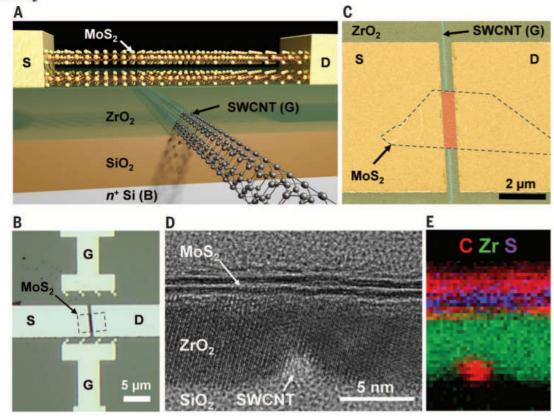


Nano-Transistors

DEVICE TECHNOLOGY

MoS₂ transistors with 1-nanometer gate lengths

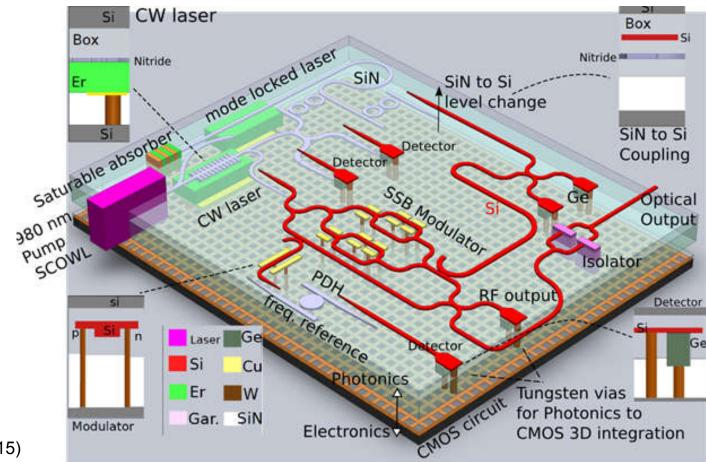
Sujay B. Desai,^{1,2,3} Surabhi R. Madhvapathy,^{1,2} Angada B. Sachid,^{1,2}
Juan Pablo Llinas,^{1,2} Qingxiao Wang,⁴ Geun Ho Ahn,^{1,2} Gregory Pitner,⁵ Moon J. Kim,⁴
Jeffrey Bokor,^{1,2} Chenming Hu,¹ H.-S. Philip Wong,⁵ Ali Javey^{1,2,3*}



Photonic Integrated Circuits

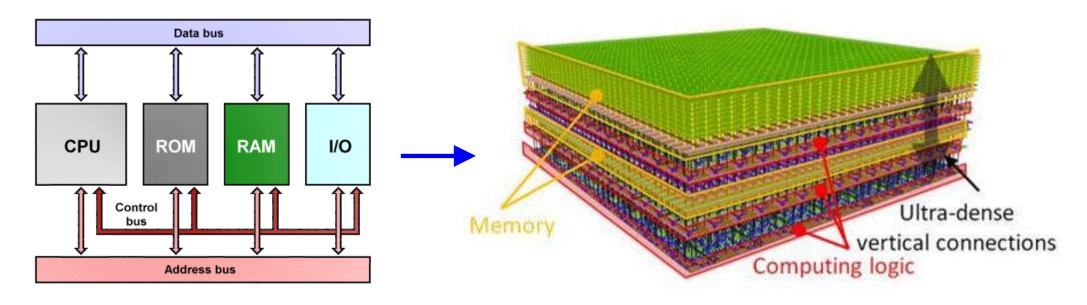
Single-chip microprocessor that communicates directly using light

Chen Sun^{1,2*}, Mark T. Wade^{3*}, Yunsup Lee^{1*}, Jason S. Orcutt²†*, Luca Alloatti², Michael S. Georgas², Andrew S. Waterman¹, Jeffrey M. Shainline³†, Rimas R. Avizienis¹, Sen Lin¹, Benjamin R. Moss², Rajesh Kumar³, Fabio Pavanello³, Amir H. Atabaki², Henry M. Cook¹, Albert J. Ou¹, Jonathan C. Leu², Yu-Hsin Chen², Krste Asanović¹, Rajeev J. Ram², Miloš A. Popović³ & Vladimir M. Stojanović¹



3D IC

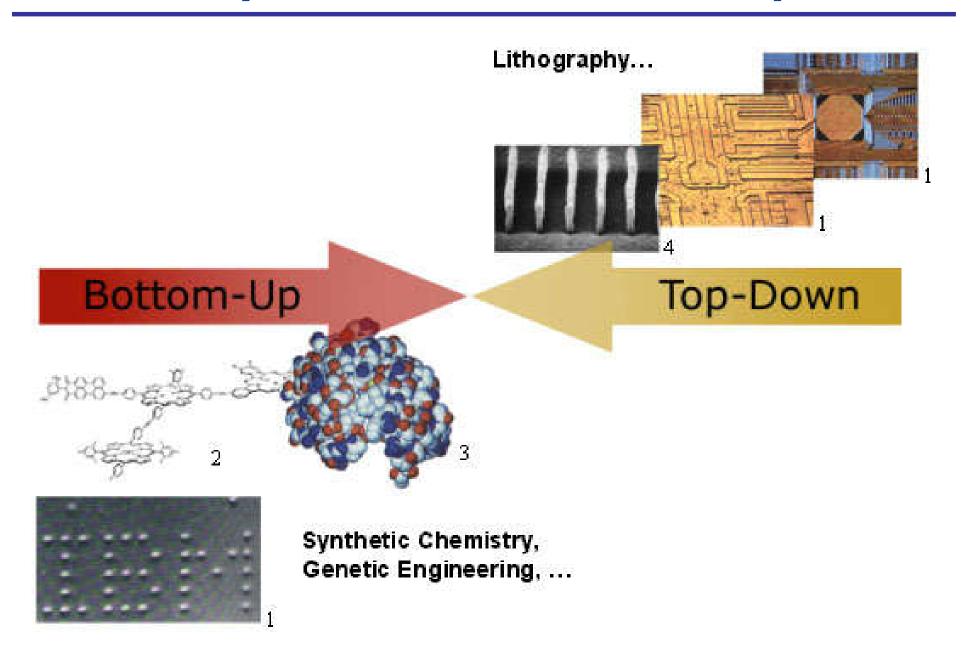
Logic + Memory + Sensing + ...



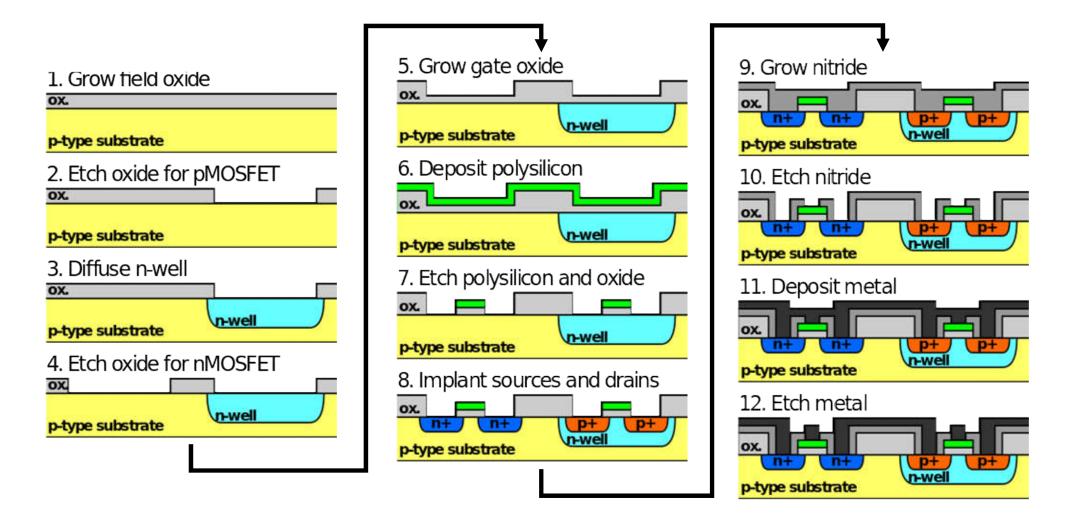
conventional

3D IC

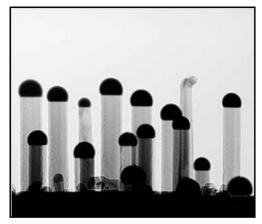
Top Down vs. Bottom Up



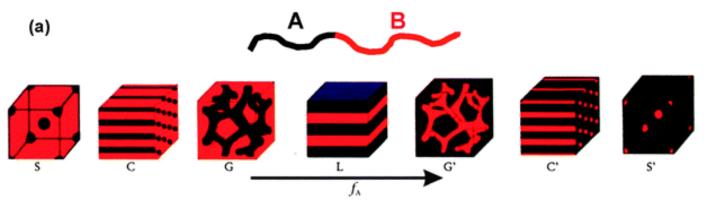
Top Down Approaches



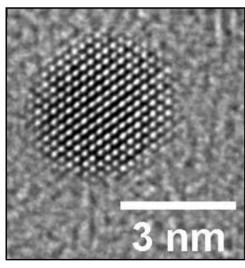
Bottom Up Approaches



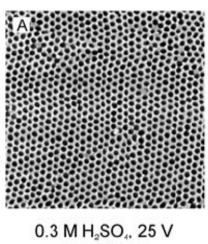
nanowire growth



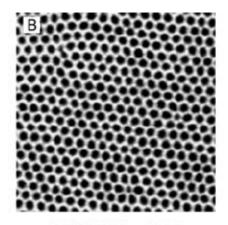
block copolymer assembly



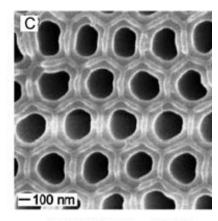
quantum dot



 $D_{c} = 60 \text{ nm}$



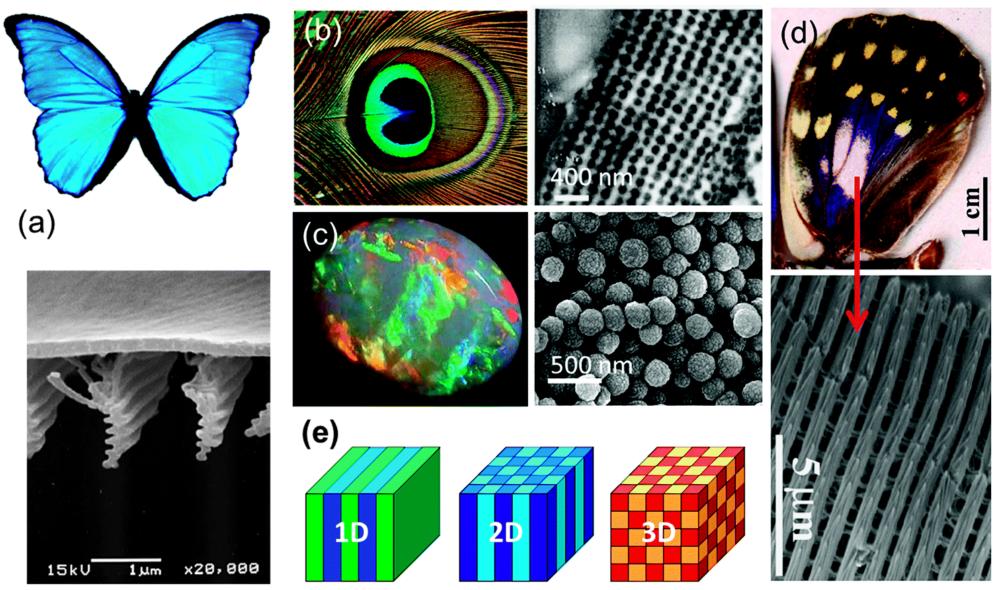
0.5 C2H2O4, 40 V $D_{c} = 100 \text{ nm}$



1.1 M H₃PO₄, 160 V $D_0 = 420 \text{ nm}$

anodized alumina

Nano Structures in Nature



Summary

"There is plenty of room at the bottom."

— Richard Feynman

"Scientists discover the world that exists; Engineers create the world that never was."

— Theodore van Karman

Thank you for your attention